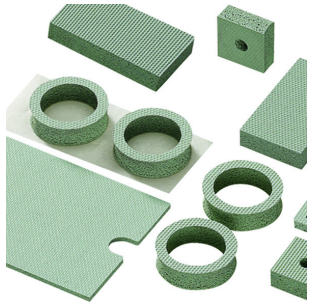


Data sheet Product WSF 635



Accessories for electronic components>Thermal interface material>Heat conductive foam and gel foils

- elastomer foam with closed cell structure
- good heat conductor e.g. between components, heatsinks and casing parts
- electrical insulating
- can be compressed even with a low contact pressure
- absorbs shocks and vibrations

Thermal resistance at 3.2 mm material thickness:

compression [%]	contact	10	25	50
contact pressure [psi]	>1	5	12	34
R_{th} [K/W] (1 in ² x 3.2 mm)	6	4.5	2.5	1
heat conductivity [W/mK]	0.3	0.4	0.45	0.65

- **WSFS 635** double sided adhesive and **WSF** self-adhesive upon request
- according to NASA gas emission requirements

Features

material:

foam film

Material:

100mm 11111

material thickness:	6.35^{±1,200} mm
version:	non adhesive
colour:	green
density:	1.105 g/cm³
hardness:	13 Shore A
temperature range:	-62°C ... +205°C
thermal conductivity:	0.108 W/m·K (substrate)
compression, 25%:	18 psi
elongation:	150 %
tear strength:	120 psi
dielectric strength:	4 kV/mm
class of inflammability:	UL 94 V-1 (at thickness ≥3.2mm)
type of delivery:	<ul style="list-style-type: none"> • plates, usable area 914x914mm • other dimensions upon request